Title: MSL level change for family of ADS78* devices in PW package  Customer Contact: PCN Manager Phone: +1(214) 480-6037 Dept: Ouality Services  Proposed 1st Ship Date: 04/11/2013 Estimated Sample Availability: 04/10/2013  Change Type:  Assembly Process	PCN Number:	20130321002				PCN Da	te:	04/10/2013	
Proposed 1st Ship Date: 04/11/2013 Estimated Sample Availability: 04/10/2013  Change Type:  Assembly Site Assembly Process Assembly Materials  Design Electrical Specification Mechanical Specification  Test Site Packing/Shipping/Labeling Test Process  Wafer Bump Site Wafer Bump Material Wafer Bump Process  Wafer Fab Site Wafer Fab Materials Wafer Fab Process  PCN Details  Description of Change:  The MSL for the ADS78* family of devices in PW package will be improved as follows:  Moisture Sensitivity Package Change From: Change To: PW Level 2-260C Level 1-260C  Reason for Change:  Devices have been qualified to MSL 1  Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):  None  Changes to product identification resulting from this PCN: Packing label on bag, box, reel will indicate: 'MS LVL:1'	Title: MSL level change for family of ADS78* devices in PW package								
Change Type:  Assembly Site	<b>Customer Contact:</b>	: PCN Manager Phone: +1(214) 480-6037 Dept: Quality Services							
Assembly Site	Proposed 1 <sup>st</sup> Ship Da	<b>te:</b> 04	/11/2013	<b>Estimate</b>	d Samp	le A	vailabilit	ty:	04/10/2013
Design	Change Type:								
Test Site    Packing/Shipping/Labeling   Test Process     Wafer Bump Site   Wafer Bump Material   Wafer Bump Process     Wafer Fab Site   Wafer Fab Materials   Wafer Fab Process     PCN Details     Description of Change:  The MSL for the ADS78* family of devices in PW package will be improved as follows:    Moisture Sensitivity   Package   Change From:   Change To:     PW   Level 2-260C   Level 1-260C     Pw   Level 2-260C   Level 1-260C     Reason for Change:  Devices have been qualified to MSL 1    Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):   None     Changes to product identification resulting from this PCN:     Packing label on bag, box, reel will indicate: 'MS LVL:1'	Assembly Site						Assembly Materials		
Wafer Bump Site Wafer Bump Material Wafer Bump Process Wafer Fab Site Wafer Fab Materials Wafer Fab Process  PCN Details  Description of Change:  The MSL for the ADS78* family of devices in PW package will be improved as follows:  Moisture Sensitivity Package Change From: Change To: PW Level 2-260C Level 1-260C  Reason for Change:  Devices have been qualified to MSL 1  Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): None  Changes to product identification resulting from this PCN: Packing label on bag, box, reel will indicate: 'MS LVL: 1'	Design						Mechanical Specification		
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Packing label on bag, box, reel will indicate: 'MS LVL:1'									
	Changes to product identification resulting from this PCN:								
Product Affected:									
	Product Affected:								
ADS7828E/250 ADS7828E/2K5G4 ADS7828EB/2K5 ADS7830IPWRG4	ADS7828E/250	ADS782	ADS7828E/2K5G4		ADS7828EB/2K5		ADS78	830IP	WRG4
ADS7828E/250G4 ADS7828EB/250 ADS7828EB/2K5G4 ADS7830IPWT	ADS7828E/250G4	ADS782	8EB/250	ADS782	8EB/2K5	ADS78	ADS7830IPWT		
ADS7828EB/250G4 ADS7830IPWR ADS7830IPWTG4	ADS7828E/2K5	ADS782	8EB/250G4	OIPWR	ADS7830IPWTG4			WTG4	

Qualifi	cation Data: Approv	red 3/XX/2	013				
This qualification has been specifically developed for the validation of this change. The qualification data							
validates that the proposed change	meets the applicable release	d technical specifi	cations.				
Qualification Device: ADS7830IPW (MSL 1-260C)							
Package Construction Details							
Assembly Site	e: TI Malaysia	Mol	ld Compound:	4206193			
# Pins-Designator, Famil	y: 16-PW, TSSOP	Lead Finish:		NiPdAu			
Qualification:  Plan  Test Results							
Reliability Test	Conditions		Sample	Size/Fail			
Reliability Test	Conditions	Lot#1	Lot#2				
**Unbiased HAST	130C/85%RH (9 <i>6</i>	78/0	80/0				
**T/C -65C/150C	-65C/+150C (500	77/0	80/0				
Manufacturability (Assembly)	(per mfg. Site specification)		pass	pass			
Moisture Sensitivity	(level 1 @ 260C peak	( +5/-0C)	pass	pass			
** - Test requires Moisture Preconditioning (MSL1-260C)							

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com